



GP1711
#5A
11/29/99
O.M.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 1711
Examiner: R. Sergeant

In Re PATENT APPLICATION OF

Applicant: LIU et al.

Serial No.: 08/958,460

Filed: October 28, 1997

For: HIGH DENSITY PLASMA
CHEMICAL VAPOR
DEPOSITION PROCESS

Atty. Docket: JIA 462

AMENDMENT

RECEIVED
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TC 1700 MAIL ROOM

BOX NON-FEE AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Official Action dated August 19, 1999, please amend the
above-referenced application as follows:

IN THE CLAIMS

1. (Amended) A method for forming conducting structures separated by gaps on
a substrate, comprising:
providing a substrate and a wiring line layer above the substrate;
forming a first antireflective coating on the wiring line layer;
forming a second antireflective coating on the first antireflective coating,
wherein the first antireflective coating and the second antireflective coating are
formed from different materials;

FEE ENCLOSED: \$ 6.11
Please charge any further
fee to our Deposit Account
No. 18-0002

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